

IN THE SPECIFICATION

Please amend the specification as follows:

[0080] After the chip and the substrate have been attached to each other, the resulting structure is as depicted in Figure 27. Then, this structure is encapsulated through any procedure known in the art. In one aspect of the invention, the encapsulation is carried out, as illustrated in Figure 28, by first applying a support film 501 to the backside of the substrate 101 ~~substrate 201~~. In one aspect of the invention, the support film is a polyimide (PI) film. Next, the molding compound 502 is applied by any known means, e.g., by transfer molding using an epoxy molding compound, by an applied liquid molding compound in a strip form, or by an array molding. After the molding compound is applied, the support film 501 is removed using any known process in the art.